#### **Features**

- Single Supply Voltage, Range 2.7V to 3.6V
- Single Supply for Read and Write
- Fast Read Access Time 70 ns
- Internal Program Control and Timer
- " internal Program Control and Time
- 8K Bytes Boot Block with Lockout
   Fast Erase Cycle Time 10 Seconds
- Byte-by-byte Programming 30 μs/Byte Typical
- Hardware Data Protection
- DATA Polling For End of Program Detection
- Low Power Dissipation
  - 25 mA Active Current
  - 50 µA CMOS Standby Current
- Typical 10,000 Write Cycles

### **Description**

The AT49BV020 and the AT49LV020 are 3-volt-only, 2-megabit Flash memories organized as 262,144 words of 8 bits each. Manufactured with Atmel's advanced non-volatile CMOS technology, the devices offer access times to 70 ns with power dissipation of just 90 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than  $50 \, \mu A$ .

To allow for simple in-system reprogrammability, the AT49BV/LV020 does not require high input voltages for programming. Three-volt-only commands determine the read and programming operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT49BV/LV020 is performed by erasing the entire 2 megabits of memory and then programming on a byte by byte basis. The typical byte programming time is a fast 30 µs. The end of a program cycle can be optionally detected by the DATA polling feature. Once the end of a byte program cycle has been detected, a new access for a read or program can begin. The typical number of program and erase cycles is in excess of 10,000 cycles.

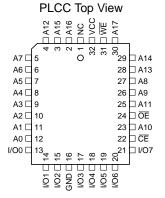
### **Pin Configuration**

VSOP Top View (8 x 14mm) or TSOP Top View (8 x 20mm) **Type 1** 

(continued)

Pin Name	Function
A0 - A17	Addresses
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

		((	
A11 🖂	1		32 🗆 ŌĒ
A9 🗀	$_{2}\bigcirc$		31 🗀 A10
A8 🗔	3		30 🗀 CE
A13 🗀	4		29 🗀 1/07
A14 🗀	5		28 🗀 I/O6
A17 🗀	6		27 🗀 I/O5
WE 🗆	7		26 🗀 I/O4
VCC □	8		25 🗀 I/O3
NC 🗀	9		24 GND
A16 🗀	10		23 🗀 I/O2
A15 🗀	11		22 🗀 I/O1
A12 🗀	12		21 🗀 I/O0
A7 🗀	13		20 🗀 A0
A6 🗀	14		19 🗀 A1
A5 🗀	15		18 🗀 A2
A4 🗀	16	( (	17 🗀 A3
'		7)	





2-megabit (256K x 8) Single 2.7-volt *Battery-Voltage*<sup>™</sup> Flash Memory

AT49BV020 AT49LV020

Rev. 0678E-08/99

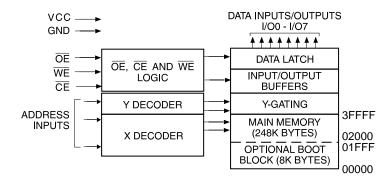




The optional 8K bytes boot block section includes a reprogramming write lock out feature to provide data integrity. The boot sector is designed to contain user secure code,

and when the feature is enabled, the boot sector is permanently protected from being reprogrammed.

#### **Block Diagram**



### **Device Operation**

**READ:** The AT49BV/LV020 is accessed like an EPROM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever CE or OE is high. This dual-line control gives designers flexibility in preventing bus contention.

**ERASURE:** Before a byte can be reprogrammed, the 256K bytes memory array (or 248K bytes if the boot block featured is used) must be erased. The erased state of the memory bits is a logical "1". The entire device can be erased at one time by using a 6-byte software code. The software chip erase code consists of 6-byte load commands to specific address locations with a specific data pattern (please refer to the Chip Erase Cycle Waveforms).

After the software chip erase has been initiated, the device will internally time the erase operation so that no external clocks are required. The maximum time needed to erase the whole chip is  $t_{\rm EC}$ . If the boot block lockout feature has been enabled, the data in the boot sector will not be erased.

BYTE PROGRAMMING: Once the memory array is erased, the device is programmed (to a logical "0") on a byte-by-byte basis. Please note that a data "0" cannot be programmed back to a "1"; only erase operations can convert "0"s to "1"s. Programming is accomplished via the internal device command register and is a 4 bus cycle operation (please refer to the Command Definitions table). The device will automatically generate the required internal program pulses.

The program cycle has addresses latched on the falling edge of WE or CE, whichever occurs last, and the data latched on the rising edge of  $\overline{\text{WE}}$  or  $\overline{\text{CE}}$ , whichever occurs first. Programming is completed after the specified  $t_{\text{BP}}$  cycle

time. The  $\overline{\text{DATA}}$  polling feature may also be used to indicate the end of a program cycle.

BOOT BLOCK PROGRAMMING LOCKOUT: The device has one designated block that has a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. The size of the block is 8K bytes. This block, referred to as the boot block, can contain secure code that is used to bring up the system. Enabling the lockout feature will allow the boot code to stay in the device while data in the rest of the device is updated. This feature does not have to be activated; the boot block's usage as a write protected region is optional to the user. The address range of the boot block is 00000H to 01FFFH.

Once the feature is enabled, the data in the boot block can no longer be erased or programmed. Data in the main memory block can still be changed through the regular programming method. To activate the lockout feature, a series of six program commands to specific addresses with specific data must be performed. Please refer to the Command Definitions table.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine if programming of the boot block section is locked out. When the device is in the software product identification mode (see Software Product Identification Entry and Exit sections) a read from address location 00002H will show if programming the boot block is locked out. If the data on I/O0 is low, the boot block can be programmed; if the data on I/O0 is high, the program lock-out feature has been activated and the block cannot be programmed. The software product identification code should be used to return to standard operation.

**PRODUCT IDENTIFICATION:** The product identification mode identifies the device and manufacturer as Atmel. It

may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

**DATA POLLING:** The AT49BV/LV020 features DATA polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. DATA polling may begin at any time during the program cycle.

**TOGGLE BIT:** In addition to DATA polling the AT49BV/LV020 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the

device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

**HARDWARE DATA PROTECTION:** Hardware features protect against inadvertent programs to the AT49BV/LV020 in the following ways: (a)  $V_{CC}$  sense: if  $V_{CC}$  is below 1.8V (typical), the program function is inhibited. (b) Program inhibit: holding any one of  $\overline{OE}$  low,  $\overline{CE}$  high or  $\overline{WE}$  high inhibits program cycles. (c) Noise filter: pulses of less than 15 ns (typical) on the  $\overline{WE}$  or  $\overline{CE}$  inputs will not initiate a program cycle.

**INPUT LEVELS:** While operating with a 2.7V to 3.6V power supply, the address inputs and control inputs ( $\overline{OE}$ , CE and WE) may be driven from 0 to 5.5V without adversely affecting the operation of the device. The I/O lines can only be driven from 0 to  $V_{CC}$  + 0.6V.

### **Command Definition (In Hex)**

Command	Bus	1st Cy		2nd Cyc		3rd Cy		4th Cy	Bus cle	5th Cy			Bus cle
Sequence	Cycles	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read	1	Addr	D <sub>OUT</sub>										
Chip Erase	6	5555	AA	2AAA	55	5555	80	5555	AA	2AAA	55	5555	10
Byte Program	4	5555	AA	2AAA	55	5555	A0	Addr	D <sub>IN</sub>				
Boot Block Lockout <sup>(1)</sup>	6	5555	AA	2AAA	55	5555	80	5555	AA	2AAA	55	5555	40
Product ID Entry	3	5555	AA	2AAA	55	5555	90						
Product ID Exit <sup>(2)</sup>	3	5555	AA	2AAA	55	5555	F0						
Product ID Exit <sup>(2)</sup>	1	XXXX	F0										

Notes:

- 1. The 8K byte boot sector has the address range of 00000H to 01FFFH.
- 2. Either one of the Product ID exit commands can be used.

### **Absolute Maximum Ratings\***

Temperature Under Bias55°C to +125°C	;
Storage Temperature65°C to +150°C	;
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V	′
All Output Voltages with Respect to Ground0.6V to $V_{\rm CC}$ + 0.6V	/
Voltage on $\overline{\text{OE}}$ with Respect to Ground0.6V to +13.5V	,

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





## **DC and AC Operating Range**

		AT49BV/LV020-70	AT49BV/LV020-90	AT49BV/LV020-12
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V Dower Cupply	AT49LV020	3.0V to 3.6V	3.0V to 3.6V	3.0V to 3.6V
V <sub>CC</sub> Power Supply	AT49BV020	2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V

# **Operating Modes**

Mode	CE	OE	WE	Ai	I/O
Read	$V_{IL}$	$V_{IL}$	V <sub>IH</sub>	Ai	D <sub>OUT</sub>
Program <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	Ai	D <sub>IN</sub>
Standby/Write Inhibit	V <sub>IH</sub>	X <sup>(1)</sup>	Х	X	High Z
Program Inhibit	Х	Х	V <sub>IH</sub>		
Program Inhibit	Х	V <sub>IL</sub>	Х		
Output Disable	Х	V <sub>IH</sub>	Х		High Z
Product Identification					
Handware		V	W	A1 - A17 = V <sub>IL</sub> , A9 = V <sub>H</sub> <sup>(3)</sup> , A0 = V <sub>IL</sub>	Manufacturer Code <sup>(4)</sup>
Hardware	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	A1 - A17 = V <sub>IL</sub> , A9 = V <sub>H</sub> , (3), A0 = V <sub>IH</sub>	Device Code (4)
Software <sup>(5)</sup>	•			A0 = V <sub>IL</sub> , A1 - A17=V <sub>IL</sub>	Manufacturer Code <sup>(4)</sup>
Soπware		A0 = V <sub>IH</sub> , A1 - A17=V <sub>IL</sub>	Device Code <sup>(4)</sup>		

Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .

2. Refer to AC Programming Waveforms.

3.  $V_H = 12.0V \pm 0.5V$ .

4. Manufacturer Code: 1FH, Device Code: 0BH

5. See details under Software Product Identification Entry/Exit.

#### **DC Characteristics**

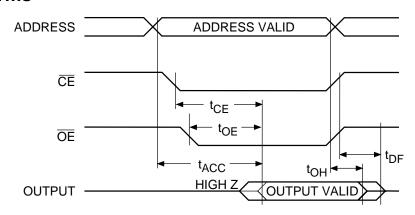
Symbol	Parameter	Condition	Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V \text{ to } V_{CC}$		10	μA
I <sub>LO</sub>	Output Leakage Current	$V_{I/O} = 0V \text{ to } V_{CC}$		10	μA
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}}$		50	μA
I <sub>SB2</sub>	V <sub>CC</sub> Standby Current TTL	CE = 2.0V to V <sub>CC</sub>		1	mA
I <sub>CC</sub> <sup>(1)</sup>	V <sub>CC</sub> Active Current	f = 5 MHz; I <sub>OUT</sub> = 0 mA		25	mA
V <sub>IL</sub>	Input Low Voltage			0.6	V
V <sub>IH</sub>	Input High Voltage		2.0		V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.45	V
V <sub>OH</sub>	Output High Voltage	$I_{OH} = -100 \ \mu A; \ V_{CC} = 3.0 V$	2.4		V

Note: 1. In the erase mode,  $I_{CC}$  is 50 mA.

#### **AC Read Characteristics**

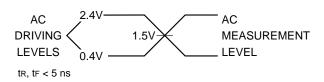
			AT49BV/LV020					
		-	-70		-90		-12	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
t <sub>ACC</sub>	Address to Output Delay		70		90		120	ns
t <sub>CE</sub> <sup>(1)</sup>	CE to Output Delay		70		90		120	ns
t <sub>OE</sub> <sup>(2)</sup>	OE to Output Delay	0	35	0	40	0	50	ns
t <sub>DF</sub> <sup>(3)(4)</sup>	CE or OE to Output Float	0	25	0	25	0	30	ns
t <sub>OH</sub>	Output Hold from OE, CE or Address, whichever occurred first	0		0		0		ns

### AC Read Waveforms<sup>(1)(2)(3)(4)</sup>

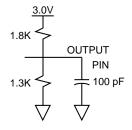


- Notes: 1.  $\overline{\text{CE}}$  may be delayed up to  $t_{\text{ACC}}$   $t_{\text{CE}}$  after the address transition without impact on  $t_{\text{ACC}}$ .
  - 2.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{CE}}$   $t_{\text{OE}}$  after the falling edge of  $\overline{\text{CE}}$  without impact on  $t_{\text{CE}}$  or by  $t_{\text{ACC}}$   $t_{\text{OE}}$  after an address change without impact on  $t_{ACC}$ .
  - 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first ( $C_L = 5pF$ ).
  - 4. This parameter is characterized and is not 100% tested.

### **Input Test Waveforms and Measurement Level**



## **Output Test Load**



## Pin Capacitance<sup>(1)</sup>

 $f = 1 \text{ MHz}, T = 25^{\circ}\text{C}$ 

Symbol	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	6	pF	V <sub>IN</sub> = 0V
C <sub>OUT</sub>	8	12	pF	V <sub>OUT</sub> = 0V

Note: 1. This parameter is characterized and is not 100% tested.



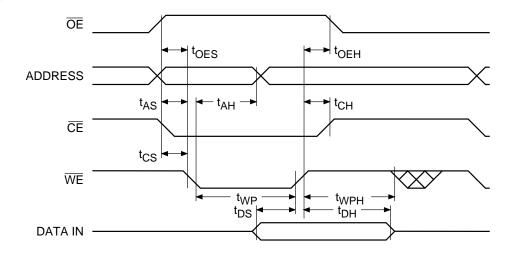


# **AC Byte Load Characteristics**

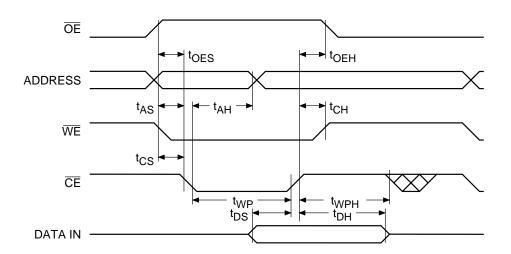
Symbol	Parameter	Min	Max	Units
$t_{AS}, t_{OES}$	Address, OE Set-up Time	0		ns
t <sub>AH</sub>	Address Hold Time	100		ns
t <sub>CS</sub>	Chip Select Set-up Time	0		ns
t <sub>CH</sub>	Chip Select Hold Time	0		ns
t <sub>WP</sub>	Write Pulse Width (WE or CE)	200		ns
t <sub>DS</sub>	Data Set-up Time	100		ns
t <sub>DH</sub> , t <sub>OEH</sub>	Data, OE Hold Time	0		ns
t <sub>WPH</sub>	Write Pulse Width High	200		ns

# **AC Byte Load Waveforms**

## WE Controlled



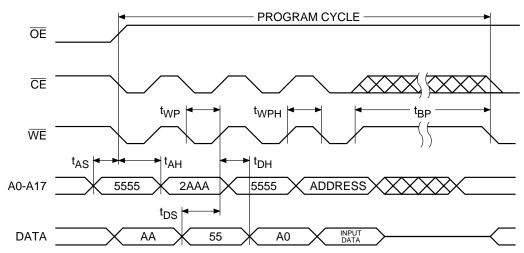
## **CE** Controlled



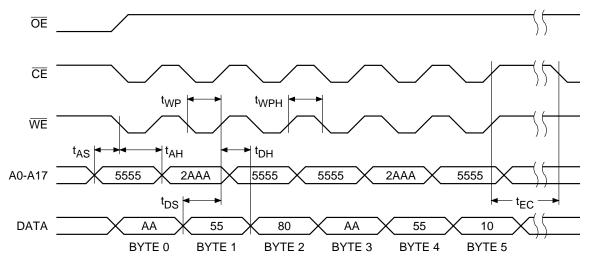
## **Program Cycle Characteristics**

Symbol	Parameter	Min	Тур	Max	Units
t <sub>BP</sub>	Byte Programming Time		30		μs
t <sub>AS</sub>	Address Set-up Time	0			ns
t <sub>AH</sub>	Address Hold Time	100			ns
t <sub>DS</sub>	Data Set-up Time	100			ns
t <sub>DH</sub>	Data Hold Time	0			ns
t <sub>WP</sub>	Write Pulse Width	200			ns
t <sub>WPH</sub>	Write Pulse Width Height	200			ns
t <sub>EC</sub>	Erase Cycle Time			10	seconds

# **Program Cycle Waveforms**



## **Chip Erase Cycle Waveforms**



Note:  $\overline{OE}$  must be high only when  $\overline{WE}$  and  $\overline{CE}$  are both low.





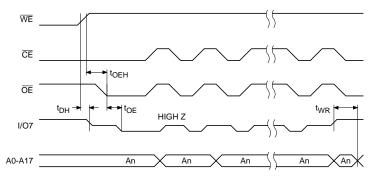
# **Data** Polling Characteristics<sup>(1)</sup>

Symbol	Parameter	Min	Тур	Max	Units
t <sub>DH</sub>	Data Hold Time	0			ns
t <sub>OEH</sub>	OE Hold Time	10			ns
t <sub>OE</sub>	OE to Output Delay <sup>(2)</sup>				ns
t <sub>WR</sub>	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See t<sub>OE</sub> spec in AC Read Characteristics.

## **Data Polling Waveforms**



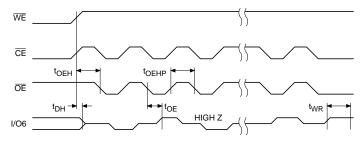
# Toggle Bit Characteristics<sup>(1)</sup>

Symbol	Parameter	Min	Тур	Max	Units
t <sub>DH</sub>	Data Hold Time	0			ns
t <sub>OEH</sub>	OE Hold Time	10			ns
t <sub>OE</sub>	OE to Output Delay <sup>(2)</sup>				ns
t <sub>OEHP</sub>	OE High Pulse	150			ns
t <sub>WR</sub>	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See  $t_{OE}$  spec in AC Read Characteristics.

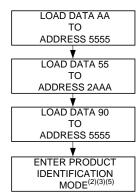
# Toggle Bit Waveforms<sup>(1)(2)(3)</sup>



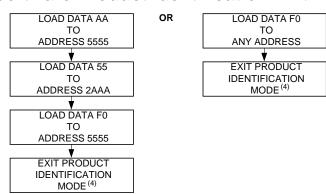
Notes: 1. Toggling either  $\overline{OE}$  or  $\overline{CE}$  or both  $\overline{OE}$  and  $\overline{CE}$  will operate toggle bit. The  $t_{OEHP}$  specification must be met by the toggling input(s).

- 2. Beginning and ending state of I/O6 will vary.
- 3. Any address location may be used but the address should not vary.

# Software Product Identification Entry<sup>(1)</sup>



## Software Product Identification Exit<sup>(1)</sup>

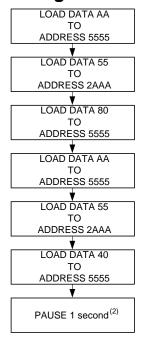


Notes: 1. Data Format: I/O7 - I/O0 (Hex); Address Format: A14 - A0 (Hex).

> 2. A1 - A17 =  $V_{IL}$ . Manufacture Code is read for A0 =  $V_{IL}$ ; Device Code is read for A0 =  $V_{IH}$ .

- 3. The device does not remain in identification mode if powered down.
- 4. The device returns to standard operation mode.
- Manufacturer Code: 1FH Device Code: 0BH

### Boot Block Lockout Feature Enable Algorithm<sup>(1)</sup>



Notes: 1. Data Format: I/O7 - I/O0 (Hex); Address Format: A14 - A0 (Hex).

2. Boot block lockout feature enabled.



# AT49BV020 Ordering Information<sup>(1)</sup>

t <sub>ACC</sub>	I <sub>CC</sub> (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
70	25	0.05	AT49BV020-70JC	32J	Commercial
			AT49BV020-70TC	32T	(0°C - 70°C)
			AT49BV020-70VC	32V	
	25	0.05	AT49BV020-70JI	32J	Industrial
			AT49BV020-70TI	32T	(-40°C - 85°C)
			AT49BV020-70VI	32V	
90	25	0.05	AT49BV020-90JC	32J	Commercial
			AT49BV020-90TC	32T	(0°C - 70°C)
			AT49BV020-90VC	32V	
	25	0.05	AT49BV020-90JI	32J	Industrial
			AT49BV020-90TI	32T	(-40°C - 85°C)
			AT49BV020-90VI	32V	
120	25	0.05	AT49BV020-12JC	32J	Commercial
			AT49BV020-12TC	32T	(0°C - 70°C)
			AT49BV020-12VC	32V	
	25	0.05	AT49BV020-12JI	32J	Industrial
			AT49BV020-12TI	32T	(-40°C - 85°C)
			AT49BV020-12VI	32V	

Note: 1. The AT49BV020 has an optional boot block feature. The part number shown in the Ordering information table is for devices with the boot block in the lower address range (i.e., 00000H to 01FFFH). Users requiring the boot block to be in the higher address range should contact Atmel

Package Type		
32J	32-lead, Plastic, J-leaded Chip Carrier Package (PLCC)	
32T	32-lead, Thin Small Outline Package (TSOP)	
32V	32-lead, Thin Small Outline Package (VSOP) (8 x 14 mm)	

# AT49LV020 Ordering Information<sup>(1)</sup>

t <sub>ACC</sub>	I <sub>CC</sub> (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
70	25	0.05	AT49LV020-70JC	32J	Commercial
			AT49LV020-70TC	32T	(0°C - 70°C)
			AT49LV020-70VC	32V	
	25	0.05	AT49LV020-70JI	32J	Industrial
			AT49LV020-70TI	32T	(-40°C - 85°C)
			AT49LV020-70VI	32V	
90	25	0.05	AT49LV020-90JC	32J	Commercial
			AT49LV020-90TC	32T	(0°C - 70°C)
			AT49LV020-90VC	32V	
	25	0.05	AT49LV020-90JI	32J	Industrial
			AT49LV020-90TI	32T	(-40°C - 85°C)
			AT49LV020-90VI	32V	
120	25	0.05	AT49LV020-12JC	32J	Commercial
			AT49LV020-12TC	32T	(0°C - 70°C)
			AT49LV020-12VC	32V	
	25	0.05	AT49LV020-12JI	32J	Industrial
			AT49LV020-12TI	32T	(-40°C - 85°C)
			AT49LV020-12VI	32V	

Note: 1. The AT49LV020 has an optional boot block feature. The part number shown in the Ordering information table is for devices with the boot block in the lower address range (i.e., 00000H to 01FFFH). Users requiring the boot block to be in the higher address range should contact Atmel

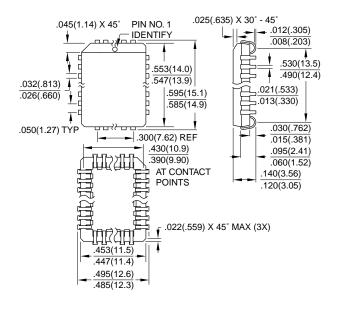
Package Type		
32J	32-lead, Plastic, J-leaded Chip Carrier Package (PLCC)	
32T	32-lead, Thin Small Outline Package (TSOP)	
32V	32-lead, Thin Small Outline Package (VSOP) (8 x 14 mm)	





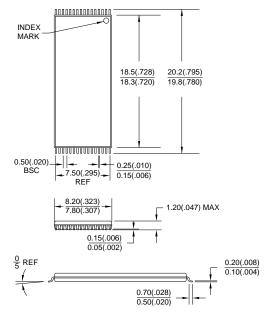
### **Packaging Information**

**32J**, 32-lead, Plastic J-leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-016 AE



**32T**, 32-lead Plastic Thin Small Outline Package (TSOP)

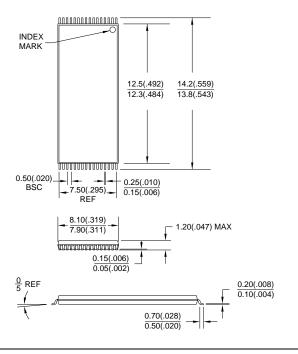
Dimensions in Millimeters and (Inches)\*
JEDEC OUTLINE MO-142 BD



\* Controlling dimension: millimeters

**32V**, 32-lead, Plastic Thin Small Outline Package (VSOP)

Dimensions in Inches and (Millimeters)
JEDEC OUTLINE MO-142 BA





#### **Atmel Headquarters**

#### **Corporate Headquarters**

2325 Orchard Parkway San Jose, CA 95131 TEL (408) 441-0311 FAX (408) 487-2600

#### Europe

Atmel U.K., Ltd.
Coliseum Business Centre
Riverside Way
Camberley, Surrey GU15 3YL
England
TEL (44) 1276-686-677
FAX (44) 1276-686-697

#### Asia

Atmel Asia, Ltd. Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimhatsui East Kowloon Hong Kong TEL (852) 2721-9778 FAX (852) 2722-1369

#### Japan

Ātmel Japan K.K. 9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan TEL (81) 3-3523-3551 FAX (81) 3-3523-7581

#### **Atmel Operations**

#### **Atmel Colorado Springs**

1150 E. Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 TEL (719) 576-3300 FAX (719) 540-1759

#### Atmel Rousset

Zone Industrielle 13106 Rousset Cedex France TEL (33) 4-4253-6000 FAX (33) 4-4253-6001

#### Fax-on-Demand

North America: 1-(800) 292-8635 International: 1-(408) 441-0732

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e-mail literature@atmel.com

Web Site http://www.atmel.com

BBS

1-(408) 436-4309

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